



Material Content Data Sheet



Sales Product Name		BSZ180P03NS3 G		Issued		29. August 2013		
MA#		MA000734042						
Package		PG-TSDSON-8-1		Weight*		36.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.936	2.59	2.59	25855	25855
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		262	
	non noble metal	iron	7439-89-6	0.189	0.52		5232	
wire	non noble metal	copper	7440-50-8	7.689	21.24	21.80	212437	217996
	non noble metal	copper	7440-50-8	0.052	0.14	0.14	1429	1429
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1023
plastics	plastics	epoxy resin	-	1.908	5.27		52707	
	inorganic material	silicondioxide	60676-86-0	16.577	45.82	51.19	457993	511723
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10225	10225
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2232	2232
solder	noble metal	silver	7440-22-4	0.029	0.08		804	
	non noble metal	tin	7440-31-5	0.023	0.06		643	
	non noble metal	lead	7439-92-1	1.111	3.07	3.21	30694	32141
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2597	
	non noble metal	copper	7440-50-8	3.816	10.54	10.81	105430	108189
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.078	0.22		2165	
	non noble metal	copper	7440-50-8	3.182	8.79	9.02	87910	90210
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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